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United States Patent [19]

Gregerson et al.

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[54] **INDIVIDUAL WAFER PACKAGE**

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[73] Assignee: **Empak, Inc.**, Chanhassen, Minn.

[**] Term: **14 Years**

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[52] **U.S. Cl.** **D9/418**; D9/432

[58] **Field of Search** D9/418, 415, 432, 337, D9/341; 206/454, 449, 45.31, 45.13, 216, 312, 313, 453, 444, 387; D3/35; D14/136, 160, 114, 164, 217

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 276,215	11/1984	Wang	D9/415
3,615,006	10/1971	Freed	206/454
3,666,140	5/1972	Brefka	206/449
4,511,038	4/1985	Miller et al.	206/454
4,664,254	5/1987	Sitwell et al.	206/454 X
4,724,960	2/1988	Goodrum et al.	206/586 X
5,045,173	9/1991	Guadagno et al.	206/454 X

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[57] **CLAIM**

The ornamental design for an individual wafer package, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of an individual wafer package showing our new design;

FIG. 2 is a left side elevational view thereof; the right side elevational view being a mirror image thereof;

FIG. 3 is a front elevational view thereof;

FIG. 4 is a rear elevational view thereof;

FIG. 5 is a top plan view thereof; and,

FIG. 6 is a bottom plan view thereof.

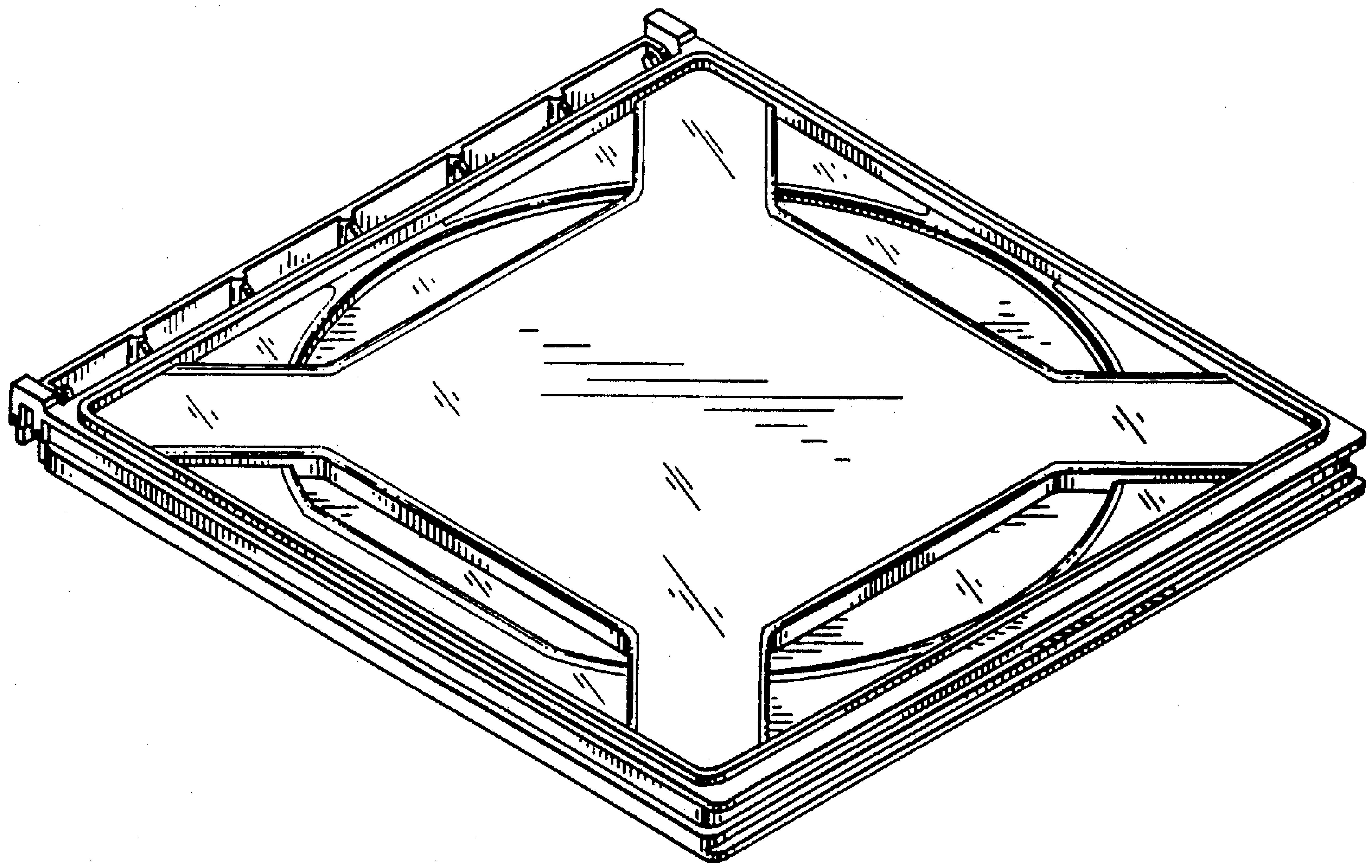

Fig.-1

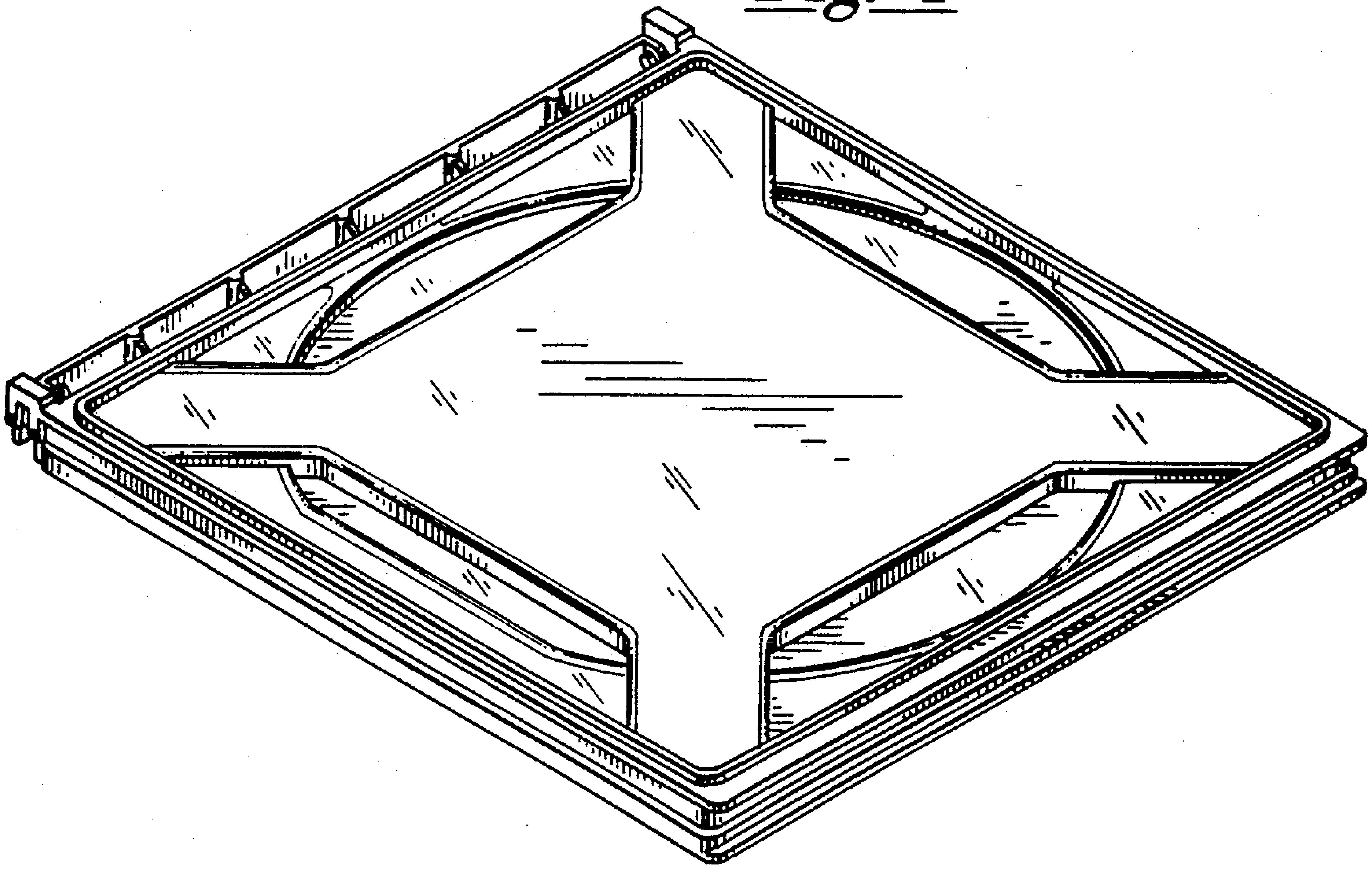

Fig.-2

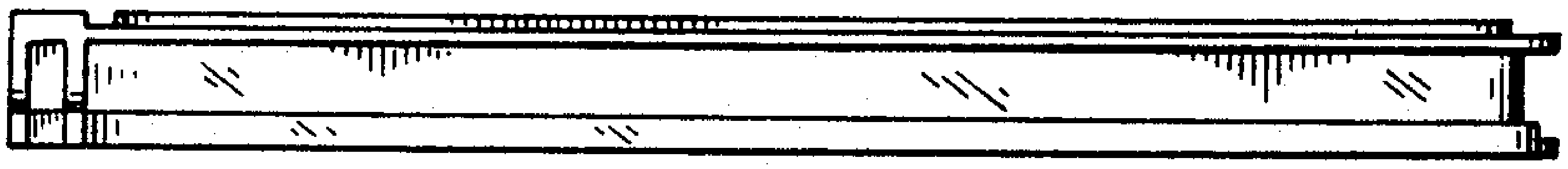

Fig.-3

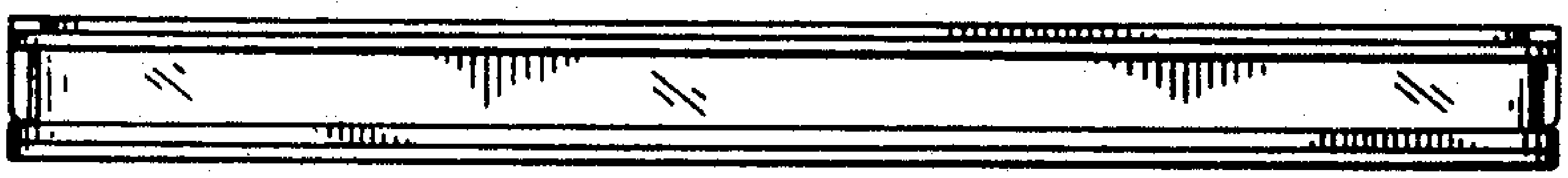

Fig.-4

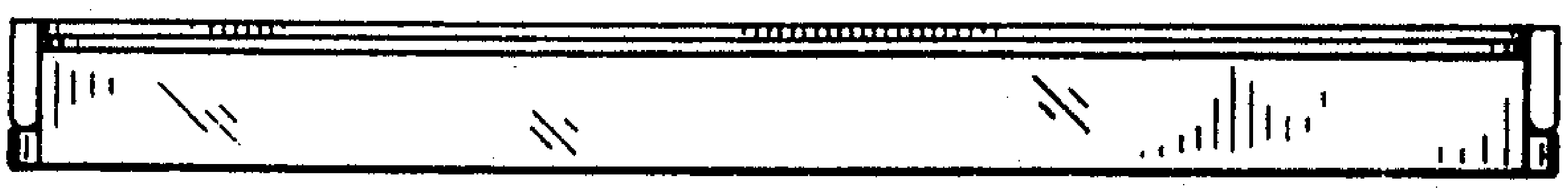

Fig.-5

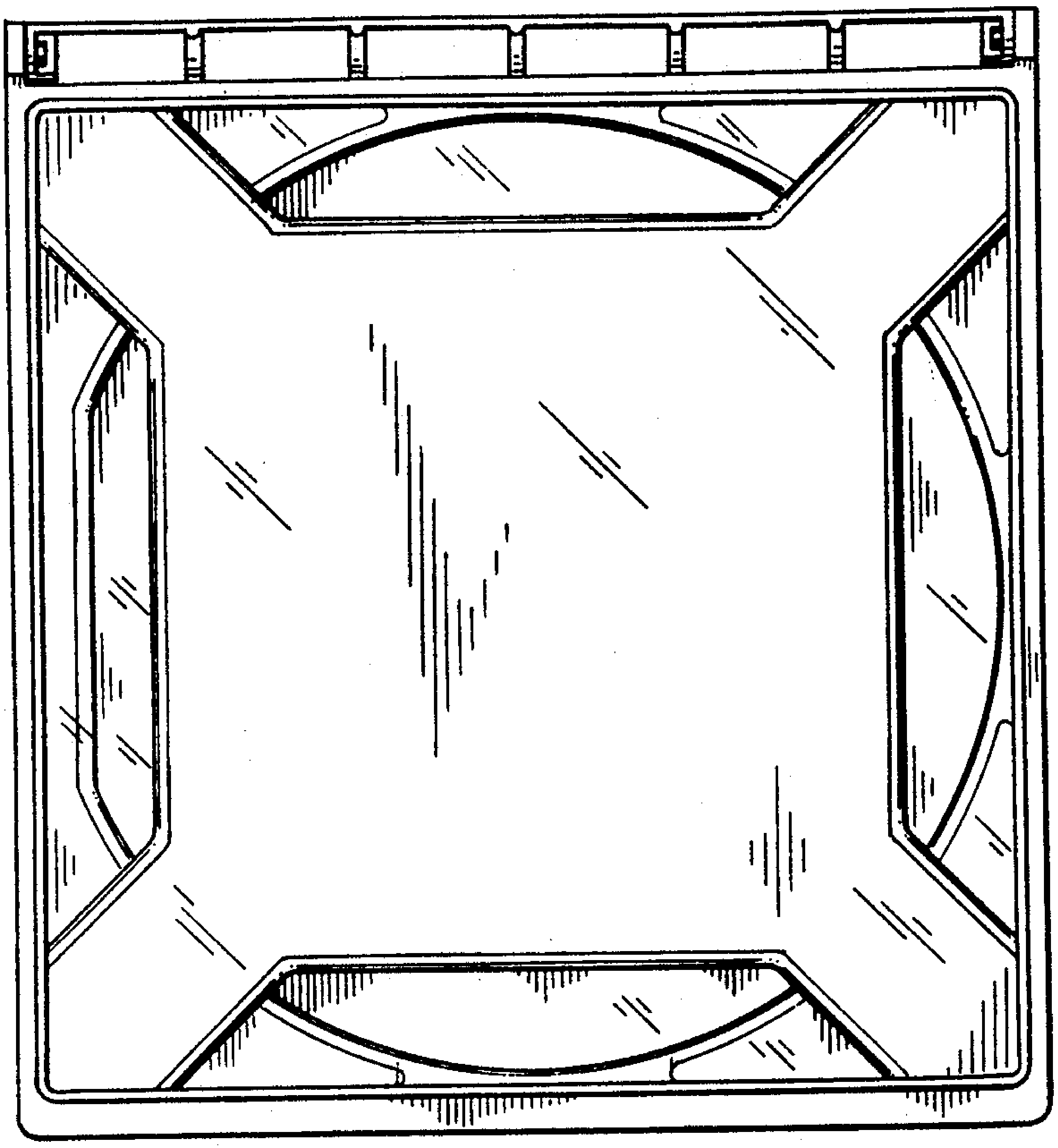

Fig.-6